

Quarterly Reliability Monitoring Results

Quarters: Q1/2022 to Q4/2023

Based on structural similarity

Supplier Nexperia B.V. Name of Laboratory Assembly reliability labs Based on AEC-Q101 Test		User Part Number						
		PESD5V0X2UAM-Q						
		Part Description						
		Nexperia DHAM Protection						
		MCD package						
		Test Conditions	Duration	# Lots	# Quantity	# Rejects		
	TEST							
	Pre- and Post-Stress							
# E1	Electrical Test	Tamb = 25 °C	N/A	see below	all parts	see below		
		JESD22-A113						
		Bake Tamb = 125 °C	24 hours					
	PC	Soak Tamb = 85 °C, RH = 85%	168 hours					
# A1	Preconditioning	Reflow soldering	3 cycles	237	10140	0		
		MIL-STD-750-1						
	HTRB	M1038 Method A						
	High Temperature Reverse Bias	Tj = Tjmax, Vr = 100% of max. datasheet				_		
# B1	Bias	reverse voltage	1000 hours	205	9400	0		
		JECD22 4404						
	TC Temperature Cycling	JESD22-A104 -65 °C to Timax, not to exceed 150°C	1000	0.6	2020	•		
# A4	remperature Cycling	-63 °C to Tjillax, flot to exceed 130°C	1000 cycles	86	3830	0		
	UHAST	JESD22-A118						
# A3 or	Unbiased HAST	Tamb = 130 °C, RH = 85 %		59	2615	0		
# A3 01	Olibidaed HAST	<u>, </u>	- 96 hours					
	AC	JESD22-A102 Tamb = 121 °C, RH = 100 %						
# A3 alt	Autoclave	Pressure = 205 kPa (29.7 psia)						
# A3 all	Addociave	11c33d1c = 203 kt d (23.7 p3id)						
	H3TRB	JESD22-A101						
	High Humidity High	Tamb = 85 °C, RH = 85%, VR = 80 % of						
# A2 alt		rated reverse voltage ^[1]	8	3 92	3695	0		
# AZ dit		MIL-STD-750 Method 1037	03 32		3033	0		
	IOL	ton = toff, devices powered to insure ΔT_j =						
# A5	Intermittent Operating Life		1000 hours	n.a.	n.a.	n.a.		
		,	2000 110013	a.				
	RSH	JESD22-A111						
# C8	Resistance to Solder Heat		10 s	n.a.	n.a.	n.a.		
50	SD		-30					
# C10	Solderability	J-STD-002		32	960	0		

^[1] The maximum applied voltage is limited by test chamber set up and does not exceed 115V.

Calculation of FIT and MTTF

Test considered for FIT calculation: High Temperature Reverse Bias (HTRB, Test #B1) Confidence level 60%, derated to 55 °C, activation energy 0.7 eV, test time 168 to 1000 hours

Wafer Fab	Technology	Quantity	Rejects	Failure Rate (FIT)	MTTF (hrs)
Nexperia					
DHAM	Protection	9400	0	0,45	2,21E+09

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